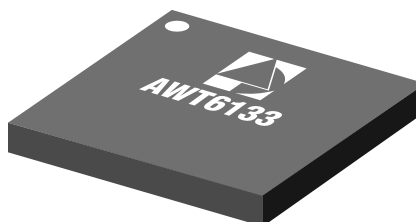


FEATURES

- InGaP HBT Technology
- High Efficiency: 38%
- Low Quiescent Current: 50 mA
- Low Leakage Current in Shutdown Mode: $<1 \mu\text{A}$
- $V_{\text{REF}} = +2.85 \text{ V}$ (+2.7 V min over temp)
- Optimized for a 50Ω System
- Low Profile Miniature Surface Mount Package: 1.56 mm Max
- CDMA 1XRTT Compliant
- CDMA 1xEV-DO Compliant

APPLICATIONS

- PCS CDMA Wireless Handsets
- Dual Band CDMA Wireless Handsets



M7 Package
10 Pin 4 mm x 4 mm x 1.5 mm
Surface Mount Module

PRODUCT DESCRIPTION

The AWT6133 meets the increasing demands for higher efficiency and linearity in CDMA 1XRTT handsets. The PA module is optimized for $V_{\text{REF}} = +2.85 \text{ V}$, a requirement for compatibility with the Qualcomm® 6000 chipset. The device is manufactured on an advanced InGaP HBT MMIC technology offering state-of-the-art reliability, temperature stability, and

ruggedness. Selectable bias modes that optimize efficiency for different output power levels, and a shutdown mode with low leakage current, increase handset talk and standby time. The self-contained 4 mm x 4 mm x 1.5 mm surface mount package incorporates matching networks optimized for output power, efficiency, and linearity in a 50Ω system.

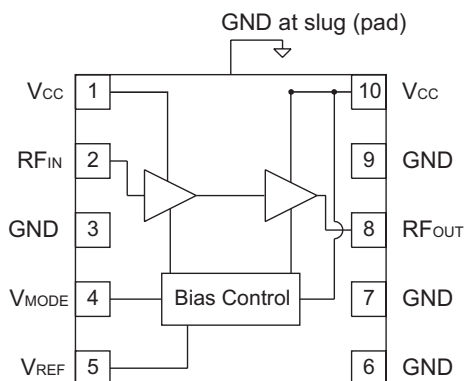


Figure 1: Block Diagram

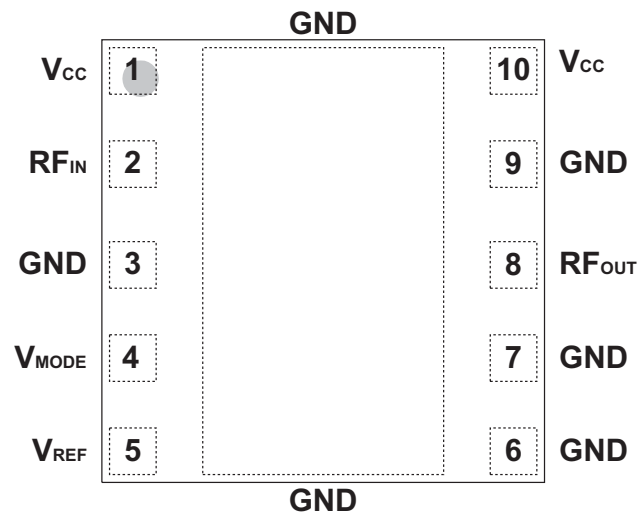


Figure 2: Pinout (X-ray Top View)

Table 1: Pin Description

PIN	NAME	DESCRIPTION
1	V _{CC}	Supply Voltage
2	RF _{IN}	RF Input
3	GND	Ground
4	V _{MODE}	Mode Control Voltage
5	V _{REF}	Reference Voltage
6	GND	Ground
7	GND	Ground
8	RF _{OUT}	RF Output
9	GND	Ground
10	V _{CC}	Supply Voltage

ELECTRICAL CHARACTERISTICS

Table 2: Absolute Minimum and Maximum Ratings

PARAMETER	MIN	MAX	UNIT
Supply Voltage (V_{CC})			
DC Only	0	+8	V
RF Drive $\leq +5$ dBm	0	+6 ⁽¹⁾	
Mode Control Voltage (V_{MODE})	0	+3.5	V
Reference Voltage (V_{REF})	0	+3.5	V
RF Input Power (P_{IN})	-	+10	dBm
Storage Temperature (T_{STG})	-40	+150	°C

Stresses in excess of the absolute ratings may cause permanent damage. Functional operation is not implied under these conditions. Exposure to absolute ratings for extended periods of time may adversely affect reliability.

Notes:

(1) $VSWR \leq 2:1$.

Table 3: Operating Ranges

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
Operating Frequency (f)	1850	-	1910	MHz	
Supply Voltage (V_{CC})	+3.2	+3.5	+4.2	V	
Reference Voltage (V_{REF})	+2.7 0	+2.85 -	+2.9 +0.5	V	PA "on" PA "shut down"
Mode Control Voltage (V_{MODE})	+2.5 0	+2.85 -	+3.1 +0.5	V	Low Bias Mode High Bias Mode
RF Output Power (P_{OUT})	+28.5 ⁽¹⁾	+29.0	-	dBm	
Case Temperature (T_C)	-30	-	+85	°C	

The device may be operated safely over these conditions; however, parametric performance is guaranteed only over the conditions defined in the electrical specifications.

Notes:

(1) For operation at $T_C = +85$ °C and $V_{CC} = +3.2$ V, P_{OUT} is derated by 0.5 dB.

Table 4: Electrical Specifications
(T_C = +25 °C, V_{CC} = +3.5 V, V_{REF} = +2.85 V, 50 Ω system)

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
Gain	25 22	27 24.5	30 27	dB	P _{OUT} = +29 dBm, V _{MODE} = 0 V P _{OUT} = +16 dBm, V _{MODE} = +2.85 V
Adjacent Channel Power ⁽¹⁾ at ± 1.25 MHz offset Primary Channel BW = 1.23 MHz Adjacent Channel BW = 30 kHz	- -	-49 -50	-47 -47	dBc	P _{OUT} = +29 dBm, V _{MODE} = 0 V P _{OUT} = +16 dBm, V _{MODE} = +2.85 V
Adjacent Channel Power at ± 2.25 MHz offset Primary Channel BW = 1.23 MHz Adjacent Channel BW = 30 kHz	- -	-60 -65	-57 -57	dBc	P _{OUT} = +29 dBm, V _{MODE} = 0 V P _{OUT} = +16 dBm, V _{MODE} = +2.85 V
Power-Added Efficiency ⁽¹⁾	36 7.25	38 8	- -	%	P _{OUT} = +29.5 dBm, V _{MODE} = 0 V P _{OUT} = +16 dBm, V _{MODE} = +2.85 V
Quiescent Current (I _q)	- -	110 50	125 65	mA	V _{MODE} = 0 V V _{MODE} = +2.85 V
Reference Current	-	3.7	5	mA	through V _{REF} pin, PA on
Mode Control Current	-	0.3	0.5	mA	through V _{MODE} pin, V _{MODE} = +2.85 V
Leakage Current	-	<1	5	μA	V _{CC} = +4.2 V, V _{REF} = 0 V V _{MODE} = 0 V
Noise in Receive Band 1930 MHz to 1990 MHz	-	-136	-134	dBm/Hz	
Harmonics 2fo 3fo, 4fo	- -	-45 -55	-30 -30	dBc	
Input Impedance	-	-	2:1	VSWR	
Spurious Output Level (all spurious outputs)	-	-	-65	dBc	P _{OUT} ≤ +29 dBm In-band load VSWR < 8:1 Out-of-band load VSWR 8:1 Applies over all voltage and temperature operating ranges
Load mismatch stress with no permanent degradation or failure	8:1	-	-	VSWR	V _{CC} = +5.0 V, P _{IN} = +5 dBm Applies over full operating temperature range

Notes:

(1) ACPR and PAE limits apply to middle frequency only.

APPLICATION INFORMATION

To ensure proper performance, refer to all related Application Notes on the ANADIGICS web site: <http://www.anadigics.com>

Shutdown Mode

The power amplifier may be placed in a shutdown mode by applying logic low levels (see Operating Ranges table) to both the V_{REF} and V_{MODE} voltages.

Bias Modes

The power amplifier may be placed in either a Low Bias mode or a High Bias mode by applying the appropriate logic level (see Operating Ranges table) to the V_{MODE} voltage. The Bias Control table lists the recommended modes of operation for various applications.

Table 5: Bias Control

APPLICATION	P _{OUT} LEVELS	BIAS MODE	V _{REF}	V _{MODE}
CDMA - low power	≤+16dBm	Low	+2.85 V	+2.85 V
CDMA - high power	>+16 dBm	High	+2.85 V	0 V
Shutdown	-	Shutdown	0 V	0 V

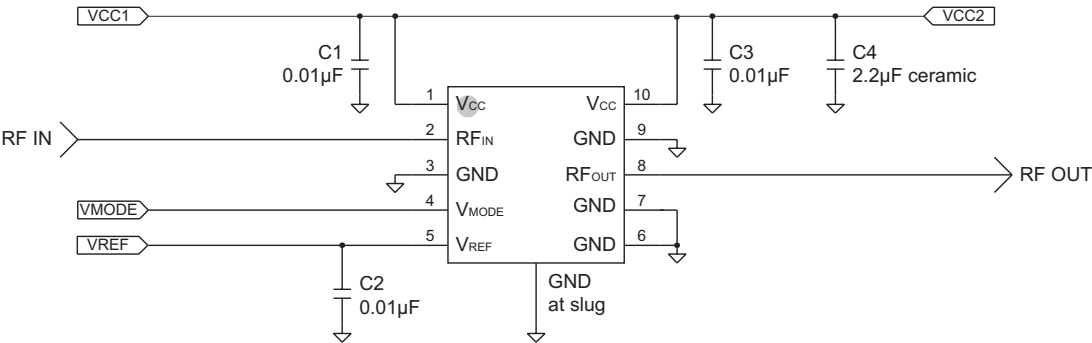
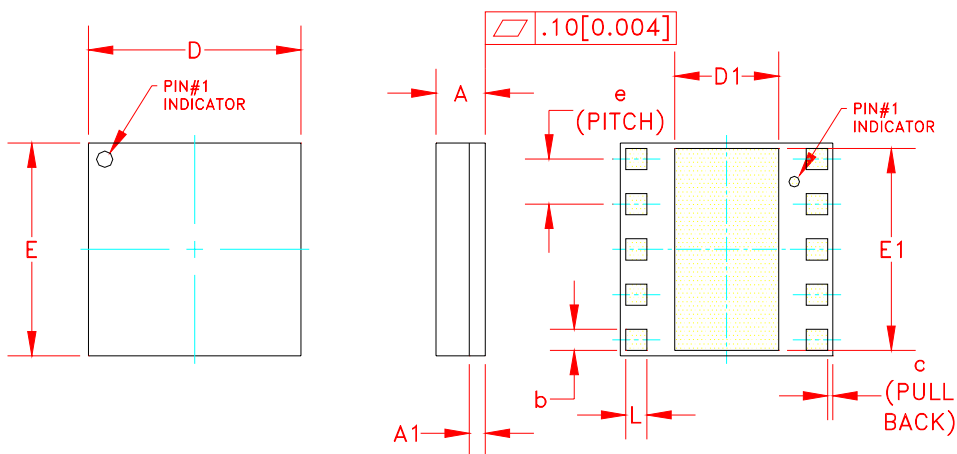


Figure 3: Application Circuit Schematic

PACKAGE OUTLINE



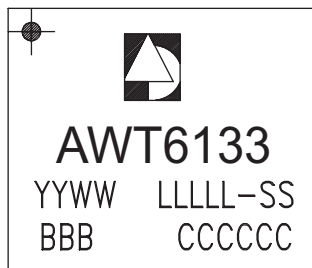
	MILLIMETERS			INCHES			NOTE
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	1.26	1.41	1.56	0.049	0.055	0.061	—
A1	—	0.30	—	—	0.012	—	—
b	0.35	—	0.60	0.013	—	0.024	3
c	—	0.10	—	—	0.004	—	—
D	3.88	4.00	4.12	0.152	0.157	0.162	—
D1	1.90	—	2.20	0.075	—	0.086	—
E	3.88	4.00	4.12	0.152	0.157	0.162	—
E1	3.75	—	3.85	0.148	—	0.152	—
e	—	0.85	—	—	0.033	—	3
L	0.35	—	0.60	0.013	—	0.024	3

NOTES:

1. CONTROLLING DIMENSIONS: MILLIMETERS
2. UNLESS SPECIFIED TOLERANCE=±0.076[0.003].
3. PADS (INCLUDING CENTER) SHOWN UNIFORM SIZE FOR REFERENCE ONLY. ACTUAL PAD SIZE AND LOCATION WILL VARY WITHIN MIN. AND MAX. DIMENSIONS ACCORDING TO SPECIFIC LAMINATE DESIGN.

Figure 4: M7 Package Outline - 10 Pin 4 mm x 4 mm x 1.5 mm Surface Mount Module

TOP BRAND

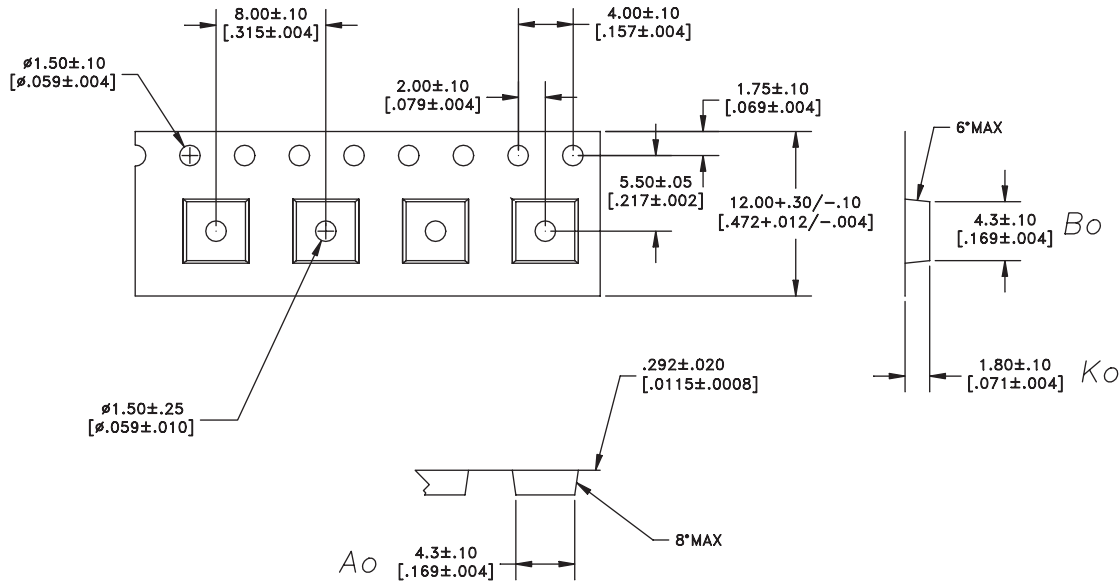


NOTES:

1. ANADIGICS LOGO SIZE: X=0.040±0.010 Y=0.048±0.010
2. PART # AWT6133
3. YEAR AND WORK WEEK: YYWW: YY = YEAR, WW = WORK WEEK
4. LOT - WAFER I.D.: LLLLL - SS = WAFER/LOT I.D.
5. PIN 1 INDICATOR: MOLD NOTCH —or— INK DOT
6. BOM # BBB
7. COUNTRY CODE: CCCCC
8. TYPE : ELITE
SIZE : AS LARGE AS POSSIBLE
LASER MARKED

Figure 5: Branding Specification

COMPONENT PACKAGING



DIMENSIONS ARE IN MILLIMETERS [INCHES]
STANDARD TOLERANCES

Figure 6: Tape & Reel Packaging

Table 6: Tape & Reel Dimensions

PACKAGE TYPE	TAPE WIDTH	POCKET PITCH	REEL CAPACITY	MAX REEL DIA
4 mm x 4 mm x 1.5 mm	12 mm	8 mm	2500	13"

ORDERING INFORMATION

ORDER NUMBER	TEMPERATURE RANGE	PACKAGE DESCRIPTION	COMPONENT PACKAGING
AWT6133M7P8	-30 °C to +85 °C	10 Pin 4 mm x 4 mm x 1.5 mm Surface Mount Module	Tape and Reel, 2500 pieces per Reel

**ANADIGICS, Inc.**

141 Mount Bethel Road
Warren, New Jersey 07059, U.S.A.
Tel: +1 (908) 668-5000
Fax: +1 (908) 668-5132

URL: <http://www.anadigics.com>
E-mail: Mktg@anadigics.com

IMPORTANT NOTICE

ANADIGICS, Inc. reserves the right to make changes to its products or to discontinue any product at any time without notice. The product specifications contained in Advanced Product Information sheets and Preliminary Data Sheets are subject to change prior to a product's formal introduction. Information in Data Sheets have been carefully checked and are assumed to be reliable; however, ANADIGICS assumes no responsibilities for inaccuracies. ANADIGICS strongly urges customers to verify that the information they are using is current before placing orders.

WARNING

ANADIGICS products are not intended for use in life support appliances, devices or systems. Use of an ANADIGICS product in any such application without written consent is prohibited.